

Declaration of Compliance

We declare that our green products for customer comply with all RoHS regulations. We are willing to provide all necessary documentation or information to prove our compliance with the RoHS regulations. It is our responsibility to proactively inform our customer if we identify that there is a potential risk of breaching the RoHS regulations in our product.

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|---|--------|------|--------|-------|
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Product Model P/N: AS9716-32D

Product Description: 400GbE Datacenter Switch

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Edge-Core Networks approve and follow the exclude article of EU RoHS for components and product.

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|------|--|
| | a. Full compliance with RoHS 2.0(2011/65/EU&(EU)2015/863&EN50581:2012) |
| | Pb, Hg, Cr6+, PBB, PBDE, DEHP, DBP, BBP, DIBP < 1000 ppm, Cd < 100 ppm |
| | b. Full compliance with RoHS 2.0(2011/65/EU&(EU)2015/863&EN50581:2012) |
| | Pb, Hg, Cr6+, PBB, PBDE, DEHP, DBP, BBP, DIBP < 1000 ppm, Cd < 100 ppm+PFOS(2006/122/EC)(PFOS < 1000 ppm) |
| 40 | C. FullI compliance with China RoHS requirements (Pb, Hg, Cr6+, PBB, PBDE < 1000 ppm, Cd < 100 ppm) |
| | d. FullI compliance with Korea RoHS requirements (Pb, Hg, Cr6+, PBB, PBDE < 1000 ppm, Cd < 100 ppm) |
| | e. FullI compliance with REACH(EC 1907/2006)requirements |
| | f. Fulll compliance with Taiwan RoHS-CNS 15663 requirements |
| | g. Others |

RoHS:

Meet RoHS 2(2011/65/EU & (EU)2015/863) and use RoHS Exemption as below:

6(c): Copper alloy containing up to 4 % lead by weight.

7(a): Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead) .

7(c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.



China RoHS:

| 产品内含危害物质揭露表 Products contain hazardous substances exposing table | | | | | | | |
|--|-------------------------------------|-----------|-----------|---------------|---------------|------------------|--|
| | 危害物质项目 Hazardous Substances Project | | | | | | |
| 零部件名称 Component Name | 铅 (Pb) | 镉 (Cd) | 汞 (Hg) | 六价铬 (Cr6+) | 多溴联苯 (PBB) | 多溴二苯乙醚 (PBDE) | |
| 固态硬盘模块SSD Module | Х | 0 | 0 | 0 | 0 | 0 | |
| 动态随机存取内存模块SDRAM Module | Х | 0 | 0 | 0 | 0 | 0 | |
| 电源供应器 Power supply | X | 0 | 0 | 0 | 0 | 0 | |
| 风扇FAN | X | 0 | 0 | 0 | 0 | 0 | |
| 间隔柱SPACER | Х | 0 | 0 | 0 | 0 | 0 | |
| 螺丝帽NUT | Х | 0 | 0 | 0 | 0 | 0 | |
| 石英震荡器Crystal | Х | 0 | 0 | 0 | 0 | 0 | |
| 电压转换集成电路 Regulator | Х | 0 | 0 | 0 | 0 | 0 | |
| 电阻 Resistor | Х | 0 | 0 | 0 | 0 | 0 | |

本表格依据 SJ/T: 11364-2014 的规定编制。

〇:表示此部件使用的所有同类材料中此种有毒或有害物质的含量均低于 GB/T 26572-2011 规定的限制要求。

O: indicates the toxic or hazardous substance content of the part (at the homogenous material level) is lower than the threshold defined by Requirements for Concentration Limits for Toxic or hazardous Substances in Electronic Information Products(GB/T 26572-2011) issued by Chinese Ministry of Information Industry ("Not Contained" toxic or hazardous substances).

X:表示此部件使用的至少一种同类材料中·此种有毒或有害物质的含量高于 GB/T 26572-2011 规定的限制要求。

X: indicates the toxic or hazardous substance content of the part (at the homogenous material level) is over the threshold defined by standard of GB/T 26572-2011("Contained" toxic or hazardous substances). Suppliers can explain the technical cause of "X" according to actual situation.



REACH:

This statement reflects Products listed below that are manufactured by Accton Technology corporation are in compliance to Regulation (EC) No 1907/2006 of the European Parliament and of the Council of 18 December 2006 concerning the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH). Substances of Very High Concern Candidate List by ECHA with latest publication date Jun 25 2020.

According to the Article 33.2 of Regulation (EC) No1907/2006:

The manufacturer has the obligation for safety use to provide sufficient information to the consumer/recipient of the article if Substances of Very High Concern (SVHC) conform to the standard of Article 57 and the regulation of Article 59 (1) are contained in its products in a concentration above 0.1% weight by weight (w/w).

Accton will focus on the subject continually and conduct SVHC inventory accounting via supplier chain. And some measure be take and discuss the possibility of substitute with supplier if necessary.

Accton has identified materials within its products that may contain EU REACH SVHC candidate substances in excess of 0.1% by weight. The substances are:

| SVHCs in a concentration above 0.1% weight by weight | CAS No. |
|---|------------|
| Cobalt(II) sulphate | 10124-43-3 |
| 1-methyl-2-pyrrolidone | 872-50-4 |
| Diboron trioxide | 1303-86-2 |
| 1,3,5-Tris(oxiran-2-ylmethyl)-1,3,5-triazinane-2,4,6-trione (TGIC) | 2451-62-9 |
| 1,2-dimethoxyethane; ethylene glycol dimethyl ether (EGDME) | 110-71-4 |
| Lead oxide (lead monoxide) | 1317-36-8 |
| Hexahydro-4-methylphathalic anhydride, | 19438-60-9 |
| Cyclohexane-1,2-dicarboxylic anhydride (HHPA), cis-cyclohexane-1,2- | 85-42-7 |
| dicarboxylic anhydride, transcyclohexane- | |
| Lead titanium trioxide | 12060-00-3 |
| Lead | 7439-92-1 |
| 2-methyl-1-(4-methylthiophenyl)-2-morpholinopropan-1-one | 71868-10-5 |
| 2-methylimidazole | 693-98-1 |



Taiwan RoHS:

限用物質含有情況標示聲明書

Declaration of the Presence Condition of the Restricted Substances Marking

| 設備名稱:400G | 乙太網路交換 | 桑器 | 型號(型式):AS9716-32D | | | | | | |
|------------------------------------|--|------------------|-------------------------|---|--|--|--|--|--|
| Equipment name | | | Type designation (Type) | | | | | | |
| | 限用物質及其化學符號 Restricted substances and its chemical symbols | | | | | | | | |
| 單元Unit | 鉛Lead (Pb) | 汞Mercury (Hg) | 鎘 Cadmium (Cd) | 六價鉻 Hexavalent chromium (Cr+6) | 多溴聯苯 Polybrominated biphenyls (PBB) | 多溴二苯醚 Polybrominated diphenyl ethers (PBDE) | | | |
| 電路板組件 PCBA | - | 0 | 0 | 0 | 0 | 0 | | | |
| 固態硬碟模組 SSD Module | E. | 0 | 0 | 0 | 0 | 0 | | | |
| 動態隨機存取記 憶體模組 SDRAM Module | - | 0 | 0 | 0 | 0 | 0 | | | |
| 機殼 Chassis | - | 0 | 0 | 0 | 0 | 0 | | | |
| 線材 Cable | 0 | 0 | 0 | 0 | 0 | 0 | | | |
| 電源供應器 Power Supply | - | 0 | 0 | 0 | 0 | 0 | | | |
| 風扇 FAN | - | 0 | 0 | 0 | 0 | 0 | | | |

備考1. "超出0.1 wt %"及 "超出0.01 wt %" 係指限用物質之百分比含量超出百分比含量基準值。

Note 1: "Exceeding 0.1 wt %" and "exceeding 0.01 wt %" indicate that the percentage content of the restricted substance exceeds the reference percentage value of presence condition.

備考2. "〇"係指該項限用物質之百分比含量未超出百分比含量基準值。

Note 2: "O" indicates that the percentage content of the restricted substance does not exceed the percentage of reference value of presence.

備考3. "-"係指該項限用物質為排除項目。

Note 3: The "-" indicates that the restricted substance corresponds to the exemption.



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